

PMEG2015EH; PMEG2015EJ

20 V, 1.5 A very low V_F MEGA Schottky barrier rectifiers

Rev. 03 — 15 January 2010

Product data sheet

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifiers with an integrated guard ring for stress protection encapsulated in small and flat SMD plastic packages.

Table 1. Product overview

| Type number | Package | | Configuration |
|-------------|---------|-------|---------------|
| | NXP | JEITA | |
| PMEG2015EH | SOD123F | - | single diode |
| PMEG2015EJ | SOD323F | SC-90 | single diode |

1.2 Features

- Forward current: ≤ 1.5 A
- Reverse voltage: ≤ 20 V
- Very low forward voltage
- Small and flat lead SMD plastic packages

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Inverse polarity protection
- Low and medium power general applications

1.4 Quick reference data


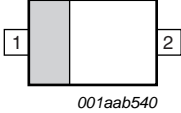
Table 2. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--------|-----------------|---------------------|-----|-----|-----|------|
| I_F | forward current | $T_{sp} \leq 55$ °C | - | - | 1.5 | A |
| V_R | reverse voltage | | - | - | 20 | V |
| V_F | forward voltage | $I_F = 1.5$ A | [1] | 560 | 660 | mV |

[1] Pulse test: $t_p \leq 300$ μ s; $\delta \leq 0.02$.

2. Pinning information

Table 3. Pinning

| Pin | Description | Simplified outline | Symbol |
|-----|-------------|--|---|
| 1 | cathode | [1] |  sym001 |
| 2 | anode |  001aab540 | |

[1] The marking bar indicates the cathode.

3. Ordering information

Table 4. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| PMEG2015EH | - | plastic surface mounted package; 2 leads | SOD123F |
| PMEG2015EJ | SC-90 | plastic surface mounted package; 2 leads | SOD323F |

4. Marking

Table 5. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMEG2015EH | AD |
| PMEG2015EJ | EL |

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------------------|---|-------|------|------|
| V_R | reverse voltage | | - | 20 | V |
| I_F | forward current | $T_{sp} \leq 55\text{ °C}$ | - | 1.5 | A |
| I_{FRM} | repetitive peak forward current | $t_p \leq 1\text{ ms}$; $\delta \leq 0.25$ | - | 5.5 | A |
| I_{FSM} | non-repetitive peak forward current | square wave; $t_p = 8\text{ ms}$ | [1] - | 9 | A |
| P_{tot} | total power dissipation | $T_{amb} \leq 25\text{ °C}$ | [1] - | 375 | mW |
| | | | [2] - | 830 | mW |
| | | | [1] - | 360 | mW |
| | | | [2] - | 830 | mW |
| T_j | junction temperature | | - | 150 | °C |
| T_{amb} | ambient temperature | | -65 | +150 | °C |

Table 6. Limiting values ...continued

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|---------------------|------------|-----|------|------|
| T_{stg} | storage temperature | | -65 | +150 | °C |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

6. Thermal characteristics

Table 7. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit | | |
|----------------|--|-------------|------------|--------|-----|------|-----|-----|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | | | | | | |
| | | | PMEG2015EH | [1][2] | - | - | 330 | K/W |
| | | | | [2][3] | - | - | 150 | K/W |
| | | | PMEG2015EJ | [1][2] | - | - | 350 | K/W |
| | | | [2][3] | - | - | 150 | K/W | |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | | | | | | |
| | | PMEG2015EH | | - | - | 60 | K/W | |
| | | PMEG2015EJ | | - | - | 55 | K/W | |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] For Schottky barrier diodes thermal run-away has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses. Nomograms for determining the reverse power losses P_R and $I_{F(AV)}$ rating are available on request.

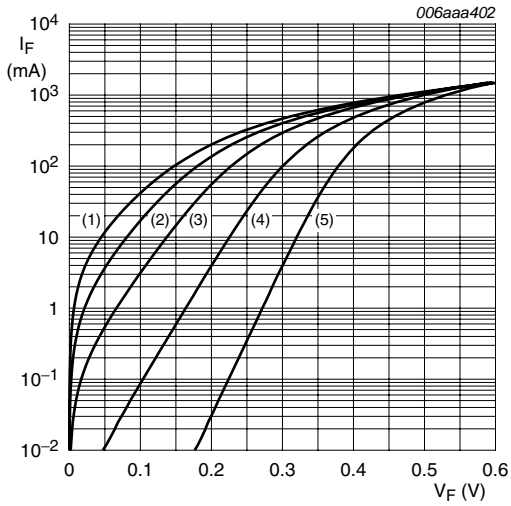
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

7. Characteristics

Table 8. Characteristics $T_{amb} = 25$ °C unless otherwise specified.

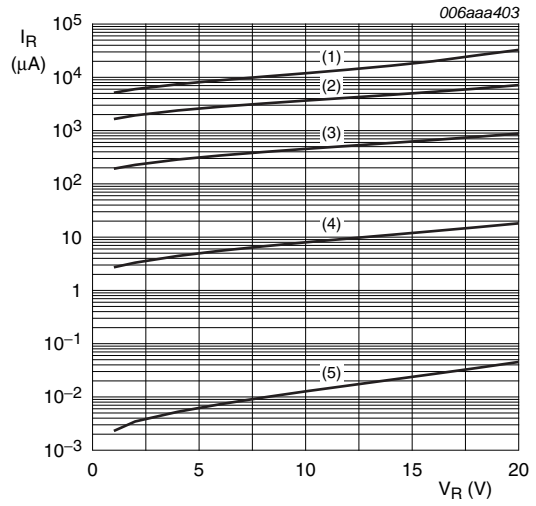
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit | |
|--------|-------------------|--------------------------|-----|-----|-----|------|----|
| V_F | forward voltage | $I_F = 10$ mA | [1] | - | 240 | 270 | mV |
| | | $I_F = 100$ mA | [1] | - | 300 | 350 | mV |
| | | $I_F = 500$ mA | [1] | - | 400 | 460 | mV |
| | | $I_F = 1$ A | [1] | - | 480 | 550 | mV |
| | | $I_F = 1.5$ A | [1] | - | 560 | 660 | mV |
| I_R | reverse current | $V_R = 5$ V | | - | 5 | 10 | μA |
| | | $V_R = 8$ V | | - | 7 | 20 | μA |
| | | $V_R = 10$ V | | - | 8 | 30 | μA |
| | | $V_R = 15$ V | | - | 10 | 50 | μA |
| | | $V_R = 20$ V | | - | 15 | 70 | μA |
| C_d | diode capacitance | $V_R = 1$ V; $f = 1$ MHz | | - | 40 | 50 | pF |

[1] Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.



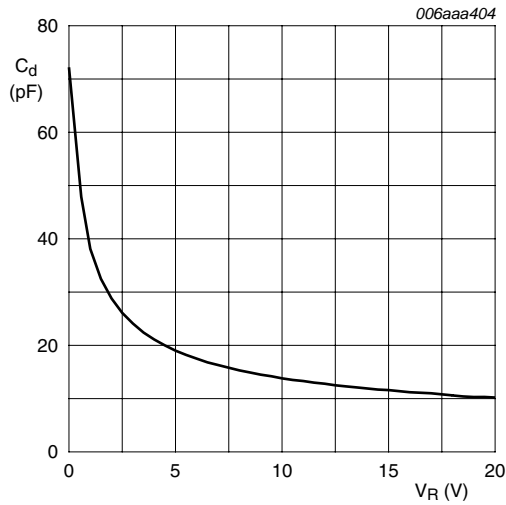
- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 125\text{ °C}$
- (3) $T_{amb} = 85\text{ °C}$
- (4) $T_{amb} = 25\text{ °C}$
- (5) $T_{amb} = -40\text{ °C}$

Fig 1. Forward current as a function of forward voltage; typical values



- (1) $T_{amb} = 150\text{ °C}$
- (2) $T_{amb} = 125\text{ °C}$
- (3) $T_{amb} = 85\text{ °C}$
- (4) $T_{amb} = 25\text{ °C}$
- (5) $T_{amb} = -40\text{ °C}$

Fig 2. Reverse current as a function of reverse voltage; typical values



$T_{amb} = 25\text{ °C}; f = 1\text{ MHz}$

Fig 3. Diode capacitance as a function of reverse voltage; typical values

8. Package outline

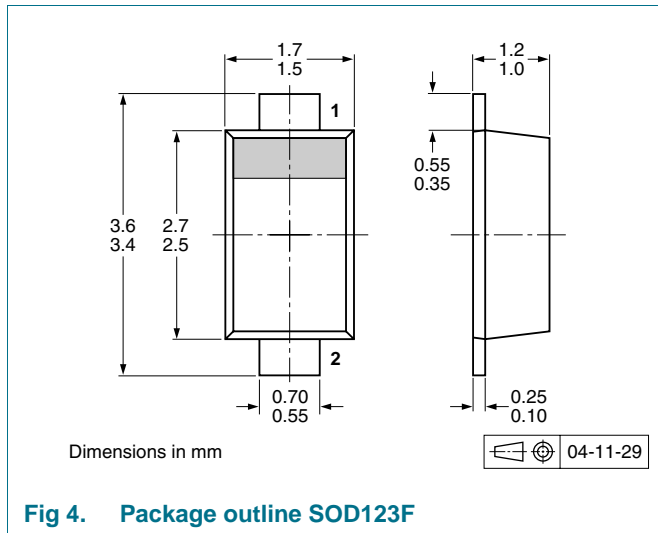


Fig 4. Package outline SOD123F

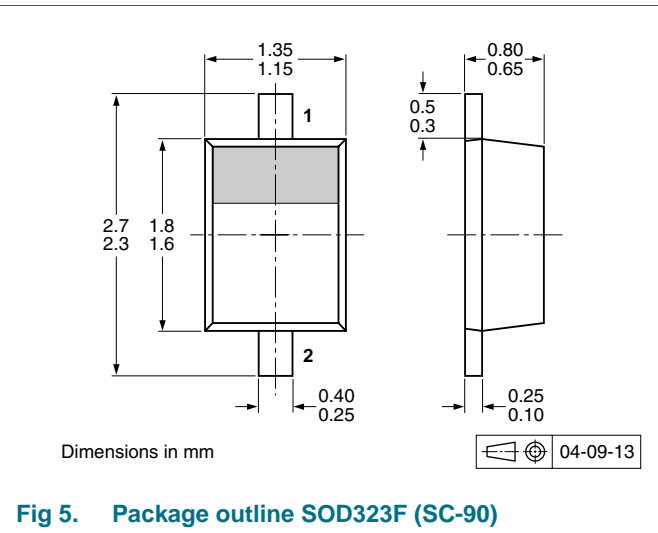


Fig 5. Package outline SOD323F (SC-90)

9. Packing information

Table 9. Packing methods

The -xxx numbers are the last three digits of the 12NC ordering code.^[1]

| Type number | Package | Description | Packing quantity | |
|-------------|---------|--------------------------------|------------------|-------|
| | | | 3000 | 10000 |
| PMEG2015EH | SOD123F | 4 mm pitch, 8 mm tape and reel | -115 | -135 |
| PMEG2015EJ | SOD323F | | | |

[1] For further information and the availability of packing methods, see [Section 13](#).

10. Soldering

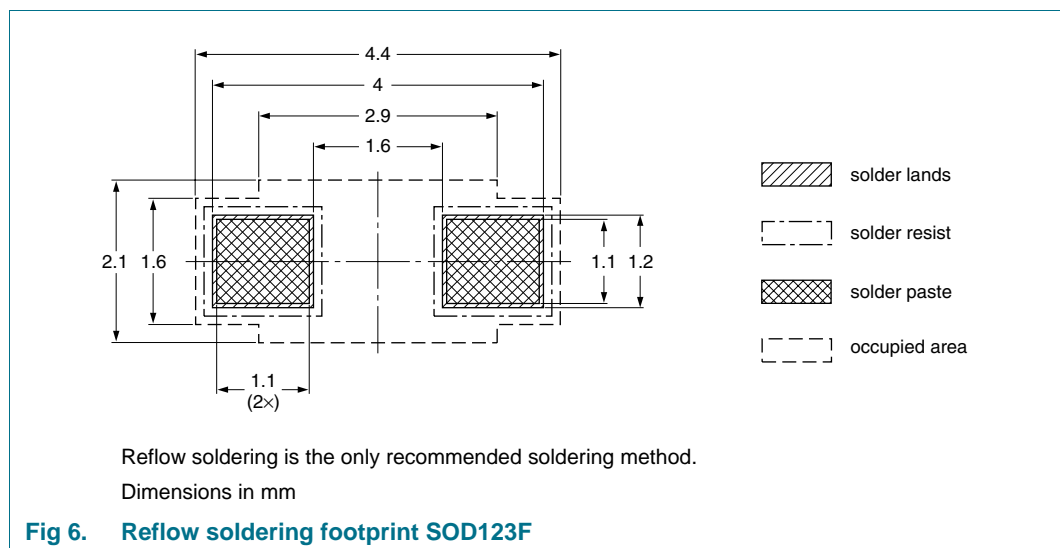
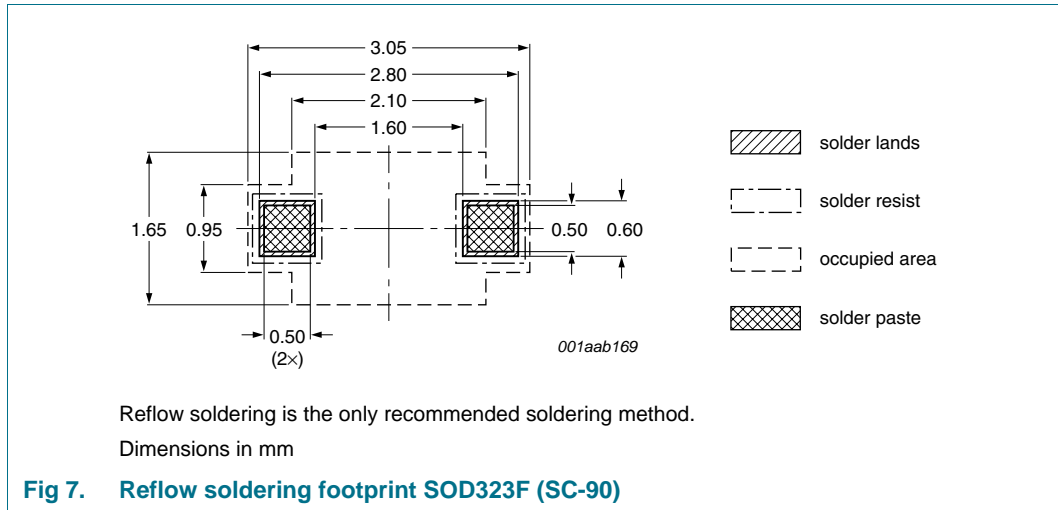


Fig 6. Reflow soldering footprint SOD123F



11. Revision history

Table 10. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-----------------|---|--------------------|---------------|-----------------|
| PMEG2015EH_EJ_3 | 20100115 | Product data sheet | - | PMEG2015EH_EJ_2 |
| Modifications: | <ul style="list-style-type: none">This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. | | | |
| PMEG2015EH_EJ_2 | 20050407 | Product data sheet | - | PMEG2015EJ_1 |
| PMEG2015EJ_1 | 20050302 | Product data sheet | - | - |

12. Legal information

12.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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